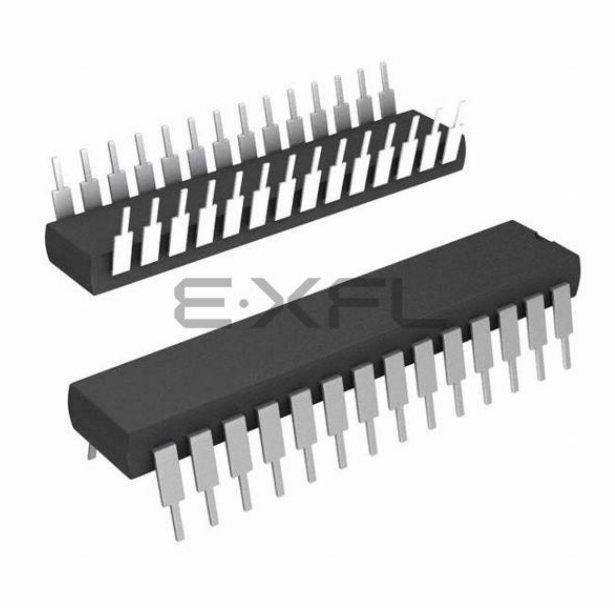


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fj16ga002-i-sp

Table of Contents

TABLE 1-2: PIC24FJ64GA004 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number			I/O	Input Buffer	Description
	28-Pin SPDIP/ SSOP/SOIC	28-Pin QFN	44-Pin QFN/TQFP			
OSCI	9	6	30	I	ANA	Main Oscillator Input Connection.
OSCO	10	7	31	O	ANA	Main Oscillator Output Connection.
PGEC1	5	2	22	I/O	ST	In-Circuit Debugger/Emulator and ICSP™ Programming Clock.
PGEC2	22	19	9	I/O	ST	
PGEC3	14	12	42	I/O	ST	
PGED1	4	1	21	I/O	ST	In-Circuit Debugger/Emulator and ICSP Programming Data.
PGED2	21	18	8	I/O	ST	
PGED3	15	11	41	I/O	ST	
PMA0	10	7	3	I/O	ST/TTL	Parallel Master Port Address Bit 0 Input (Buffered Slave modes) and Output (Master modes).
PMA1	12	9	2	I/O	ST/TTL	Parallel Master Port Address Bit 1 Input (Buffered Slave modes) and Output (Master modes).
PMA2	—	—	27	O	—	Parallel Master Port Address (Demultiplexed Master modes).
PMA3	—	—	38	O	—	
PMA4	—	—	37	O	—	
PMA5	—	—	4	O	—	
PMA6	—	—	5	O	—	
PMA7	—	—	13	O	—	
PMA8	—	—	32	O	—	
PMA9	—	—	35	O	—	
PMA10	—	—	12	O	—	
PMA11	—	—	—	O	—	
PMA12	—	—	—	O	—	
PMA13	—	—	—	O	—	
PMBE	11	8	36	O	—	Parallel Master Port Byte Enable Strobe.
PMCS1	26	23	15	O	—	Parallel Master Port Chip Select 1 Strobe/Address Bit 14.
PMD0	23	20	10	I/O	ST/TTL	Parallel Master Port Data (Demultiplexed Master mode) or Address/Data (Multiplexed Master modes).
PMD1	22	19	9	I/O	ST/TTL	
PMD2	21	18	8	I/O	ST/TTL	
PMD3	18	15	1	I/O	ST/TTL	
PMD4	17	14	44	I/O	ST/TTL	
PMD5	16	13	43	I/O	ST/TTL	
PMD6	15	12	42	I/O	ST/TTL	
PMD7	14	11	41	I/O	ST/TTL	
PMRD	24	21	11	O	—	Parallel Master Port Read Strobe.
PMWR	25	22	14	O	—	Parallel Master Port Write Strobe.

Legend: TTL = TTL input buffer ST = Schmitt Trigger input buffer
ANA = Analog level input/output I^2C™ = I^2C/SMBus input buffer

Note 1: Alternative multiplexing when the I2C1SEL Configuration bit is cleared.

2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 μF (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including microcontrollers to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μF to 47 μF.

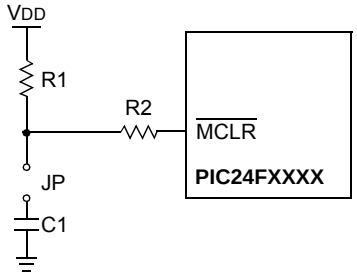
2.3 Master Clear ($\overline{MCLR}$) Pin

The $\overline{MCLR}$ pin provides two specific device functions: device Reset, and device programming and debugging. If programming and debugging are not required in the end application, a direct connection to VDD may be all that is required. The addition of other components, to help increase the application's resistance to spurious Resets from voltage sags, may be beneficial. A typical configuration is shown in Figure 2-1. Other circuit designs may be implemented, depending on the application's requirements.

During programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{MCLR}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R1 and C1 will need to be adjusted based on the application and PCB requirements. For example, it is recommended that the capacitor, C1, be isolated from the $\overline{MCLR}$ pin during programming and debugging operations by using a jumper (Figure 2-2). The jumper is replaced for normal run-time operations.

Any components associated with the $\overline{MCLR}$ pin should be placed within 0.25 inch (6 mm) of the pin.

FIGURE 2-2: EXAMPLE OF $\overline{MCLR}$ PIN CONNECTIONS



Note 1: R1 ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{MCLR}$ pin VIH and VIL specifications are met.

2: R2 ≤ 470Ω will limit any current flowing into $\overline{MCLR}$ from the external capacitor, C, in the event of $\overline{MCLR}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{MCLR}$ pin VIH and VIL specifications are met.

REGISTER 6-1: RCON: RESET CONTROL REGISTER(1) (CONTINUED)

bit 2 **IDLE:** Wake-up from Idle Flag bit
1 = Device has been in Idle mode
0 = Device has not been in Idle mode

bit 1 **BOR:** Brown-out Reset Flag bit
1 = A Brown-out Reset has occurred (note that BOR is also set after a Power-on Reset)
0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit
1 = A Power-on Reset has occurred
0 = A Power-on Reset has not occurred

Note 1: All of the Reset status bits may be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

TABLE 6-1: RESET FLAG BIT OPERATION

Flag Bit	Setting Event	Clearing Event
TRAPR (RCON<15>)	Trap Conflict Event	POR
IOPUWR (RCON<14>)	Illegal Opcode or Uninitialized W Register Access	POR
CM (RCON<9>)	Configuration Mismatch Reset	POR
EXTR (RCON<7>)	$\overline{\text{MCLR}}$ Reset	POR
SWR (RCON<6>)	RESET Instruction	POR
WDTO (RCON<4>)	WDT Time-out	PWRSAV Instruction, POR
SLEEP (RCON<3>)	PWRSAV #SLEEP Instruction	POR
IDLE (RCON<2>)	PWRSAV #IDLE Instruction	POR
BOR (RCON<1>)	POR, BOR	—
POR (RCON<0>)	POR	—

Note: All Reset flag bits may be set or cleared by the user software.

REGISTER 7-17: IPC2: INTERRUPT PRIORITY CONTROL REGISTER 2

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	U1RXIP2	U1RXIP1	U1RXIP0	—	SPI1IP2	SPI1IP1	SPI1IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	SPF1IP2	SPF1IP1	SPF1IP0	—	T3IP2	T3IP1	T3IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **U1RXIP<2:0>:** UART1 Receiver Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **SPI1IP<2:0>:** SPI1 Event Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **SPF1IP<2:0>:** SPI1 Fault Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **T3IP<2:0>:** Timer3 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 7-23: IPC8: INTERRUPT PRIORITY CONTROL REGISTER 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	SPI2IP2	SPI2IP1	SPI2IP0	—	SPF2IP2	SPF2IP1	SPF2IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-4 **SPI2IP<2:0>:** SPI2 Event Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **SPF2IP<2:0>:** SPI2 Fault Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 7-24: IPC9: INTERRUPT PRIORITY CONTROL REGISTER 9

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	IC5IP2	IC5IP1	IC5IP0	—	IC4IP2	IC4IP1	IC4IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	IC3IP2	IC3IP1	IC3IP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **IC5IP<2:0>:** Input Capture Channel 5 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **IC4IP<2:0>:** Input Capture Channel 4 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **IC3IP<2:0>:** Input Capture Channel 3 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as ‘0’

9.0 POWER-SAVING FEATURES

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"PIC24F Family Reference Manual"*, **"Power-Saving Features"** (DS39698). Additional power-saving tips can also be found in **Appendix B: "Additional Guidance for PIC24FJ64GA004 Family Applications"** of this document.

The PIC24FJ64GA004 family of devices provides the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. All PIC24F devices manage power consumption in four different ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption, while still maintaining critical application features, such as timing-sensitive communications.

9.1 Clock Frequency and Clock Switching

PIC24F devices allow for a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits. The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 8.0 "Oscillator Configuration"**.

9.2 Instruction-Based Power-Saving Modes

PIC24F devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution; Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembly syntax of the PWRSAV instruction is shown in Example 9-1.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

9.2.1 SLEEP MODE

Sleep mode includes these features:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption will be reduced to a minimum provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate during Sleep mode since the system clock source is disabled.
- The LPRC clock will continue to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals may continue to operate in Sleep mode. This includes items such as the Input Change Notification on the I/O ports, or peripherals that use an external clock input. Any peripheral that requires the system clock source for its operation will be disabled in Sleep mode.

Additional power reductions can be achieved by disabling the on-chip voltage regulator whenever Sleep mode is invoked. This is done by clearing the PMSLP bit (RCON<8>). Disabling the regulator adds an additional delay of about 190 μs to the device wake-up time. It is recommended that applications not using the voltage regulator leave the PMSLP bit set. For additional details on the regulator and Sleep mode, see **Section 24.2.5 "Voltage Regulator Standby Mode"**.

The device will wake-up from Sleep mode on any of these events:

- On any interrupt source that is individually enabled.
- On any form of device Reset.
- On a WDT time-out.

On wake-up from Sleep, the processor will restart with the same clock source that was active when Sleep mode was entered.

EXAMPLE 9-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV   #SLEEP_MODE      ; Put the device into SLEEP mode
PWRSAV   #IDLE_MODE       ; Put the device into IDLE mode
```

REGISTER 10-13: RPINR22: PERIPHERAL PIN SELECT INPUT REGISTER 22

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	SCK2R4	SCK2R3	SCK2R2	SCK2R1	SCK2R0
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	SDI2R4	SDI2R3	SDI2R2	SDI2R1	SDI2R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **SCK2R<4:0>:** Assign SPI2 Clock Input (SCK2IN) to the Corresponding RPn Pin bits

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **SDI2R<4:0>:** Assign SPI2 Data Input (SDI2) to the Corresponding RPn Pin bits

REGISTER 10-14: RPINR23: PERIPHERAL PIN SELECT INPUT REGISTER 23

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	SS2R4	SS2R3	SS2R2	SS2R1	SS2R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as '0'

bit 4-0 **SS2R<4:0>:** Assign SPI2 Slave Select Input (SS2IN) to the Corresponding RPn Pin bits

REGISTER 10-27: RPOR12: PERIPHERAL PIN SELECT OUTPUT REGISTER 12

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP25R4(1)	RP25R3(1)	RP25R2(1)	RP25R1(1)	RP25R0(1)
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP24R4(1)	RP24R3(1)	RP24R2(1)	RP24R1(1)	RP24R0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **RP25R<4:0>:** Peripheral Output Function is Assigned to RP25 Output Pin bits(1)
(see Table 10-3 for peripheral function numbers)

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **RP24R<4:0>:** Peripheral Output Function is Assigned to RP24 Output Pin bits(1)
(see Table 10-3 for peripheral function numbers)

Note 1: These bits are only available on the 44-pin devices; otherwise, they read as '0'.

14.0 OUTPUT COMPARE

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"PIC24F Family Reference Manual"*, **"Output Compare"** (DS39706).

14.1 Setup for Single Output Pulse Generation

When the OCM<2:0> control bits (OCxCON<2:0>) are set to '100', the selected output compare channel initializes the OCx pin to the low state and generates a single output pulse.

To generate a single output pulse, the following steps are required (these steps assume the timer source is initially turned off, but this is not a requirement for the module operation):

1. Determine the instruction clock cycle time. Take into account the frequency of the external clock to the timer source (if one is used) and the timer prescaler settings.
2. Calculate the time to the rising edge of the output pulse relative to the TMRy start value (0000h).
3. Calculate the time to the falling edge of the pulse based on the desired pulse width and the time to the rising edge of the pulse.
4. Write the values computed in Steps 2 and 3 above into the Output Compare x register, OCxR, and the Output Compare x Secondary register, OCxRS, respectively.
5. Set the Timery Period register, PRy, to a value equal to or greater than the value in OCxRS, the Output Compare x Secondary register.
6. Set the OCMx bits to '100' and the OCTSEL (OCxCON<3>) bit to the desired timer source. The OCx pin state will now be driven low.
7. Set the TON (TyCON<15>) bit to '1', which enables the compare time base to count.
8. Upon the first match between TMRy and OCxR, the OCx pin will be driven high.
9. When the incrementing timer, TMRy, matches the Output Compare x Secondary register, OCxRS, the second and trailing edge (high-to-low) of the pulse is driven onto the OCx pin. No additional pulses are driven onto the OCx pin and it remains at low. As a result of the second compare match event, the OCxIF interrupt flag bit is set, which will result in an interrupt if it is enabled, by setting the OCxIE bit. For further information on peripheral interrupts, refer to **Section 7.0 "Interrupt Controller"**.
10. To initiate another single pulse output, change the Timer and Compare register settings, if needed, and then issue a write to set the OCMx bits to '100'. Disabling and re-enabling the timer and clearing the TMRy register are not required, but may be advantageous for defining a pulse from a known event time boundary.

The output compare module does not have to be disabled after the falling edge of the output pulse. Another pulse can be initiated by rewriting the value of the OCxCON register.

14.2 Setup for Continuous Output Pulse Generation

When the OCM<2:0> control bits (OCxCON<2:0>) are set to '101', the selected output compare channel initializes the OCx pin to the low state and generates output pulses on each and every compare match event.

For the user to configure the module for the generation of a continuous stream of output pulses, the following steps are required (these steps assume the timer source is initially turned off, but this is not a requirement for the module operation):

1. Determine the instruction clock cycle time. Take into account the frequency of the external clock to the timer source (if one is used) and the timer prescaler settings.
2. Calculate the time to the rising edge of the output pulse relative to the TMRy start value (0000h).
3. Calculate the time to the falling edge of the pulse based on the desired pulse width and the time to the rising edge of the pulse.
4. Write the values computed in Steps 2 and 3 above into the Output Compare x register, OCxR, and the Output Compare x Secondary register, OCxRS, respectively.
5. Set the Timery Period register, PRy, to a value equal to or greater than the value in OCxRS.
6. Set the OCMx bits to '101' and the OCTSEL bit to the desired timer source. The OCx pin state will now be driven low.
7. Enable the compare time base by setting the TON (TyCON<15>) bit to '1'.
8. Upon the first match between TMRy and OCxR, the OCx pin will be driven high.
9. When the compare time base, TMRy, matches the OCxRS, the second and trailing edge (high-to-low) of the pulse is driven onto the OCx pin.
10. As a result of the second compare match event, the OCxIF interrupt flag bit set.
11. When the compare time base and the value in its respective Timery Period register match, the TMRy register resets to 0x0000 and resumes counting.
12. Steps 8 through 11 are repeated and a continuous stream of pulses is generated indefinitely. The OCxIF flag is set on each OCxRS/TMRy compare match event.

19.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"PIC24F Family Reference Manual"*, **"Real-Time Clock and Calendar (RTCC)"** (DS39696).

The Real-Time Clock and Calendar (RTCC) provides on-chip, hardware-based clock and calendar functionality with little or no CPU overhead. It is intended for applications where accurate time must be maintained for extended periods, with minimal CPU activity and with limited power resources, such as battery-powered applications.

Key features include:

- Time data in hours, minutes and seconds, with a granularity of one-half second
- 24-hour format (military time) display option
- Calendar data as date, month and year
- Automatic, hardware-based day of week and leap year calculations for dates from 2000 through 2099
- Time and calendar data in BCD format for compact firmware
- Highly configurable alarm function
- External output pin with selectable alarm signal or seconds "tick" signal output
- Time base input from Secondary Oscillator (SOSC) or the T1CK digital clock input (32.768 kHz)
- User calibration feature with auto-adjust

A simplified block diagram of the module is shown in Figure 19-1.The SOSC and RTCC will both remain running while the device is held in Reset with $\overline{\text{MCLR}}$, and will continue running after $\overline{\text{MCLR}}$ is released.

FIGURE 19-1: RTCC BLOCK DIAGRAM

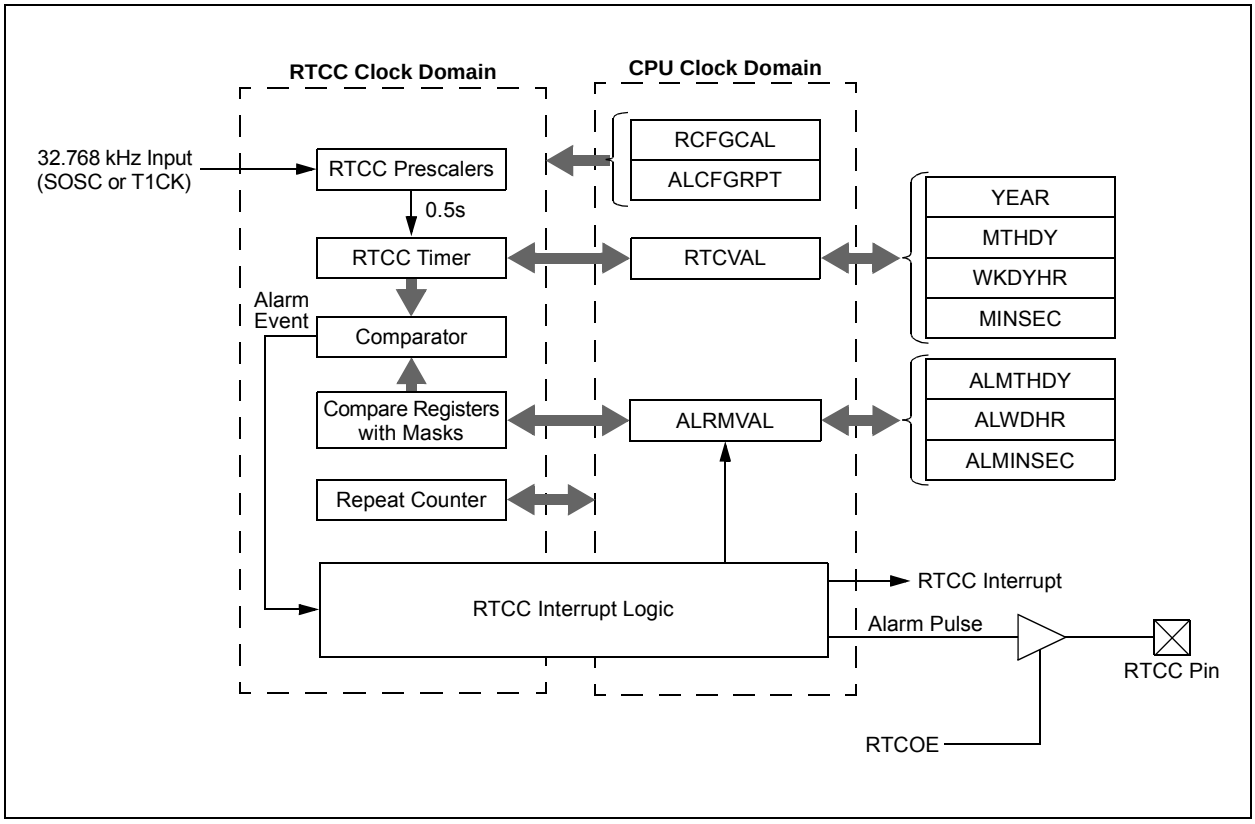
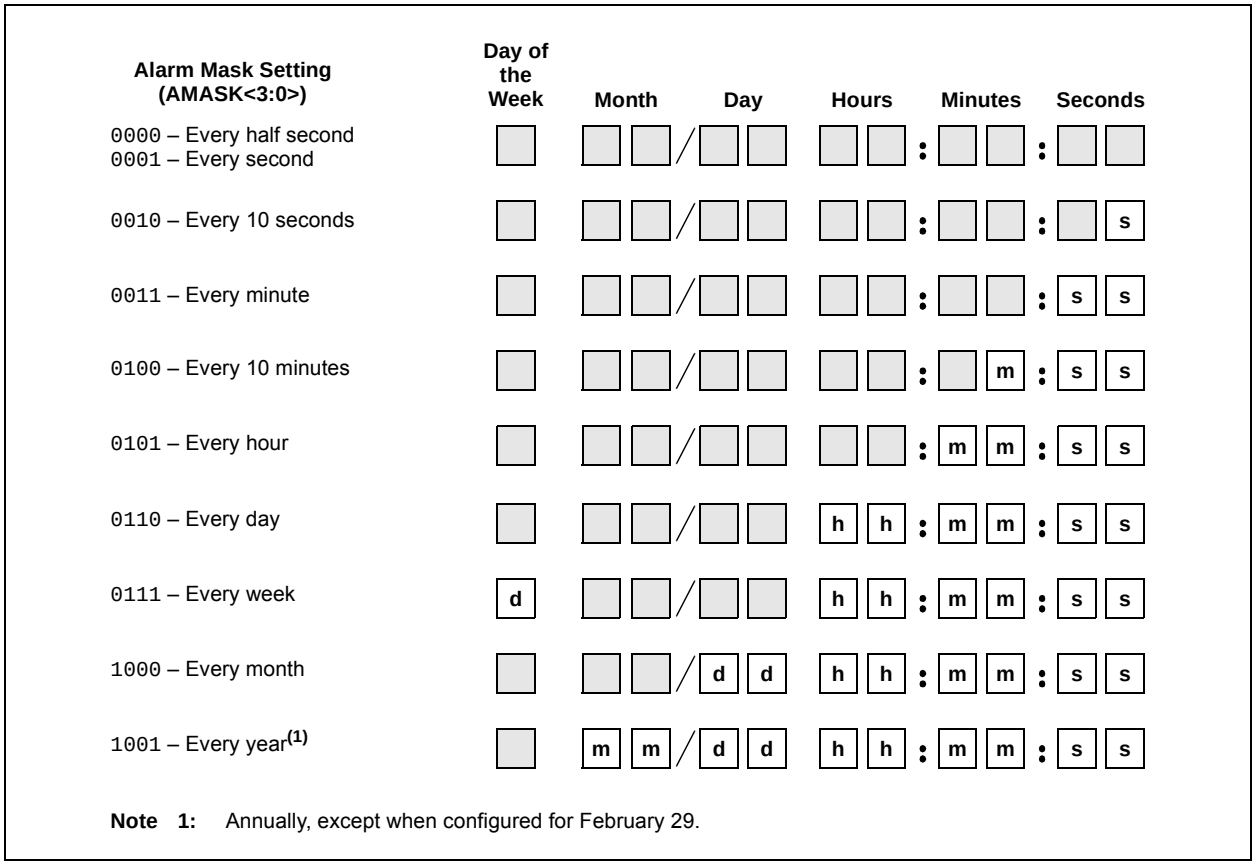


FIGURE 19-2: ALARM MASK SETTINGS



Note 1: Annually, except when configured for February 29.

REGISTER 21-4: AD1CHS: A/D INPUT SELECT REGISTER

R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB	—	—	—	CH0SB3(1,2)	CH0SB2(1,2)	CH0SB1(1,2)	CH0SB0(1,2)
bit 15							bit 8

R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA	—	—	—	CH0SA3(1,2)	CH0SA2(1,2)	CH0SA1(1,2)	CH0SA0(1,2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CH0NB:** Channel 0 Negative Input Select for MUX B Multiplexer Setting bit
1 = Channel 0 negative input is AN1
0 = Channel 0 negative input is VR-

bit 14-12 **Unimplemented:** Read as '0'

bit 11-8 **CH0SB<3:0>:** Channel 0 Positive Input Select for MUX B Multiplexer Setting bits(1,2)
1111 = Channel 0 positive input is AN15 (band gap voltage reference)
1100 = Channel 0 positive input is AN12
1011 = Channel 0 positive input is AN11
.....
0001 = Channel 0 positive input is AN1
0000 = Channel 0 positive input is AN0

bit 7 **CH0NA:** Channel 0 Negative Input Select for MUX A Multiplexer Setting bit
1 = Channel 0 negative input is AN1
0 = Channel 0 negative input is VR-

bit 6-4 **Unimplemented:** Read as '0'

bit 3-0 **CH0SA<3:0>:** Channel 0 Positive Input Select for MUX A Multiplexer Setting bits(1,2)
1111 = Channel 0 positive input is AN15 (band gap voltage reference)
1100 = Channel 0 positive input is AN12
1011 = Channel 0 positive input is AN11
.....
0001 = Channel 0 positive input is AN1
0000 = Channel 0 positive input is AN0

Note 1: Combinations, '1101' and '1110', are unimplemented; do not use.
2: Analog Channels, AN6, AN7 and AN8, are unavailable on 28-pin devices; do not use.

24.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the following sections of the *"PIC24F Family Reference Manual"*:

- **"Watchdog Timer (WDT)"** (DS39697)
- **"High-Level Device Integration"** (DS39719)
- **"Programming and Diagnostics"** (DS39716)

PIC24FJ64GA004 family devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming
- In-Circuit Emulation

24.1 Configuration Bits

The Configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1'), to select various device configurations. These bits are mapped starting at program memory location, F80000h. A complete list of locations is shown in Table 24-1. A detailed explanation of the various bit functions is provided in Register 24-1 through Register 24-4.

Note that address, F80000h, is beyond the user program memory space. In fact, it belongs to the configuration memory space (800000h-FFFFFFh), which can only be accessed using table reads and table writes.

24.1.1 CONSIDERATIONS FOR CONFIGURING PIC24FJ64GA004 FAMILY DEVICES

In PIC24FJ64GA004 family devices, the configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in the two words at the top of the on-chip program memory space, known as the Flash Configuration Words. Their specific locations are shown in Table 24-1. These are packed representations of the actual device Configuration bits, whose actual locations are distributed among five locations in configuration space. The configuration data is automatically loaded from the Flash Configuration Words to the proper Configuration registers during device Resets.

Note: Configuration data is reloaded on all types of device Resets.

TABLE 24-1: FLASH CONFIGURATION WORD LOCATIONS FOR PIC24FJ64GA004 FAMILY DEVICES

Device	Configuration Word Addresses	
	1	2
PIC24FJ16GA	002BFEh	002BFCh
PIC24FJ32GA	0057FEh	0057FCh
PIC24FJ48GA	0083FEh	0083FCh
PIC24FJ64GA	00ABFEh	00ABFCh

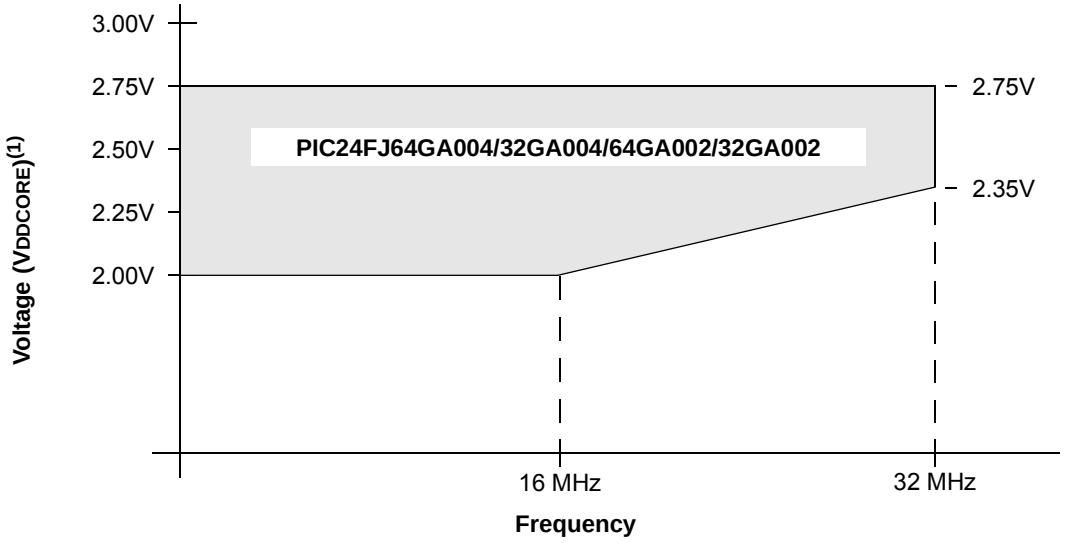
When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration Word for configuration data. This is to make certain that program code is not stored in this address when the code is compiled.

The Configuration bits are reloaded from the Flash Configuration Word on any device Reset.

The upper byte of both Flash Configuration Words in program memory should always be '1111 1111'. This makes them appear to be NOP instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '1's to these locations has no effect on device operation.

27.1 DC Characteristics

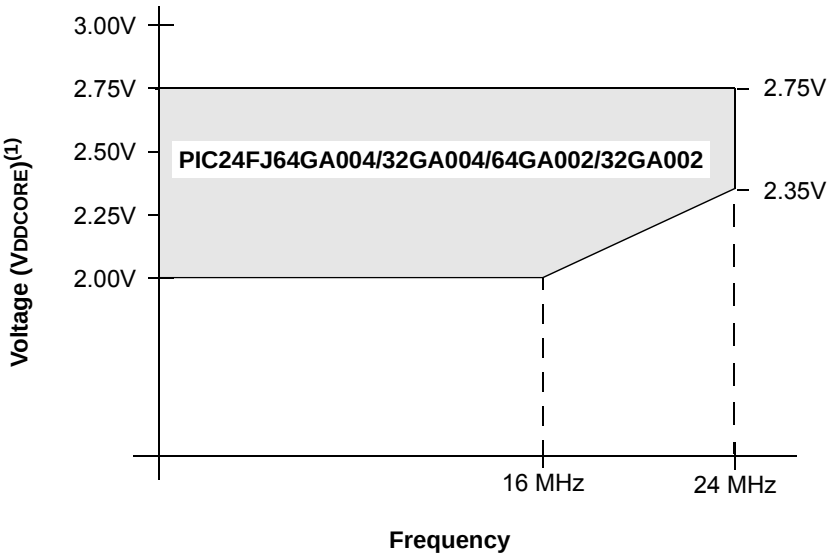
FIGURE 27-1: PIC24FJ64GA004 FAMILY VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



For frequencies between 16 MHz and 32 MHz, FMAX = (45.7 MHz/V) * (VDDCORE – 2V) + 16 MHz.

Note 1: WHEN the voltage regulator is disabled, VDD and VDDCORE must be maintained so that VDDCORE ≤ VDD ≤ 3.6V.

FIGURE 27-2: PIC24FJ64GA004 FAMILY VOLTAGE-FREQUENCY GRAPH (EXTENDED TEMPERATURE)



For frequencies between 16 MHz and 24 MHz, FMAX = (22.9 MHz/V) * (VDDCORE – 2V) + 16 MHz.

Note 1: WHEN the voltage regulator is disabled, VDD and VDDCORE must be maintained so that VDDCORE ≤ VDD ≤ 3.6V.

TABLE 27-6: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Power-Down Current (I_{PD}): PMD Bits are Set, PMSLP Bit is '0'(2)						
DC60	0.1	1	µA	-40°C	2.0V(3)	Base Power-Down Current(5)
DC60a	0.15	1	µA	+25°C		
DC60m	2.2	7.4	µA	+60°C		
DC60b	3.7	12	µA	+85°C		
DC60j	15	50	µA	+125°C		
DC60c	0.2	1	µA	-40°C	2.5V(3)	
DC60d	0.25	1	µA	+25°C		
DC60n	2.6	15	µA	+60°C		
DC60e	4.2	25	µA	+85°C		
DC60k	16	100	µA	+125°C		
DC60f	3.3	9	µA	-40°C	3.3V(4)	
DC60g	3.5	10	µA	+25°C		
DC60o	6.7	22	µA	+60°C		
DC60h	9	30	µA	+85°C		
DC60l	36	120	µA	+125°C		
DC61	1.75	3	µA	-40°C	2.0V(3)	Watchdog Timer Current: ΔI_{WDT}(5)
DC61a	1.75	3	µA	+25°C		
DC61m	1.75	3	µA	+60°C		
DC61b	1.75	3	µA	+85°C		
DC61j	3.5	6	µA	+125°C		
DC61c	2.4	4	µA	-40°C	2.5V(3)	
DC61d	2.4	4	µA	+25°C		
DC61n	2.4	4	µA	+60°C		
DC61e	2.4	4	µA	+85°C		
DC61k	4.8	8	µA	+125°C		
DC61f	2.8	5	µA	-40°C	3.3V(4)	
DC61g	2.8	5	µA	+25°C		
DC61o	2.8	5	µA	+60°C		
DC61h	2.8	5	µA	+85°C		
DC61l	5.6	10	µA	+125°C		

Note 1: Data in the Typical column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Base I_{PD} is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled high. WDT, etc., are all switched off.

3: On-chip voltage regulator is disabled (DISVREG tied to V_{DD}).

4: On-chip voltage regulator is enabled (DISVREG tied to V_{SS}). Low-Voltage Detect (LVD) and Brown-out Detect (BOD) are enabled.

5: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

TABLE 27-7: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DI31	IPU	**Maximum Load Current for Digital High Detection with Internal Pull-up**	—	—	30	µA	VDD = 2.0V
			—	—	100	µA	VDD = 3.3V
	IIL	**Input Leakage Current(2,3)**					
DI50		I/O Ports	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI55		$\overline{\text{MCLR}}$	—	—	±1	µA	VSS ≤ VPIN ≤ VDD
DI56		OSCI	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, XT and HS modes
DI60a	IICL	**Input Low Injection Current**	0	—	-5(5,8)	mA	All pins except VDD, VSS, AVDD, AVSS, $\overline{\text{MCLR}}$, VCAP, RB11, SOSCI, SOSCO, D+, D-, VUSB, and VBUS
DI60b	IICH	**Input High Injection Current**	0	—	+5(6,7,8)	mA	All pins except VDD, VSS, AVDD, AVSS, $\overline{\text{MCLR}}$, VCAP, RB11, SOSCI, SOSCO, D+, D-, VUSB, and VBUS, and all 5V tolerant pins(7)
DI60c	∑IICT	**Total Input Injection Current** (sum of all I/O and control pins)	-20(9)	—	+20(9)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| IICL + | IICH |) ≤ ∑IICT)

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: Refer to Table 1-2 for I/O pin buffer types.

5: Parameter is characterized but not tested.

6: Non-5V tolerant pins, VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

7: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources greater than 5.5V.

8: Injection currents > | 0 | can affect the performance of all analog peripherals (e.g., A/D, comparators, internal band gap reference, etc.)

9: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 27-10: COMPARATOR SPECIFICATIONS

Operating Conditions: 2.0V < VDD < 3.6V, -40°C < TA < +85°C (unless otherwise stated)							
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Comments**
D300	VIOFF	Input Offset Voltage*	—	10	30	mV	
D301	VICM	Input Common-Mode Voltage*	0	—	VDD	V	
D302	CMRR	Common-Mode Rejection Ratio*	55	—	—	dB	
300	TRESP	Response Time*(1)	—	150	400	ns	
301	TMC2OV	Comparator Mode Change to Output Valid*	—	—	10	μs	

* Parameters are characterized but not tested.

Note 1: Response time is measured with one comparator input at (VDD – 1.5)/2, while the other input transitions from VSS to VDD.

TABLE 27-11: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

Operating Conditions: 2.0V < VDD < 3.6V, -40°C < TA < +85°C (unless otherwise stated)							
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Comments**
VRD310	CVRES	Resolution	VDD/24	—	VDD/32	LSb	
VRD311	CVRAA	Absolute Accuracy	—	—	1	LSb	
VRD312	CVRUR	Unit Resistor Value (R)	—	2k	—	Ω	
VR310	TSET	Settling Time(1)	—	—	10	μs	

Note 1: Settling time is measured while CVRR = 1 and the CVR<3:0> bits transition from '0000' to '1111'.

TABLE 27-12: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

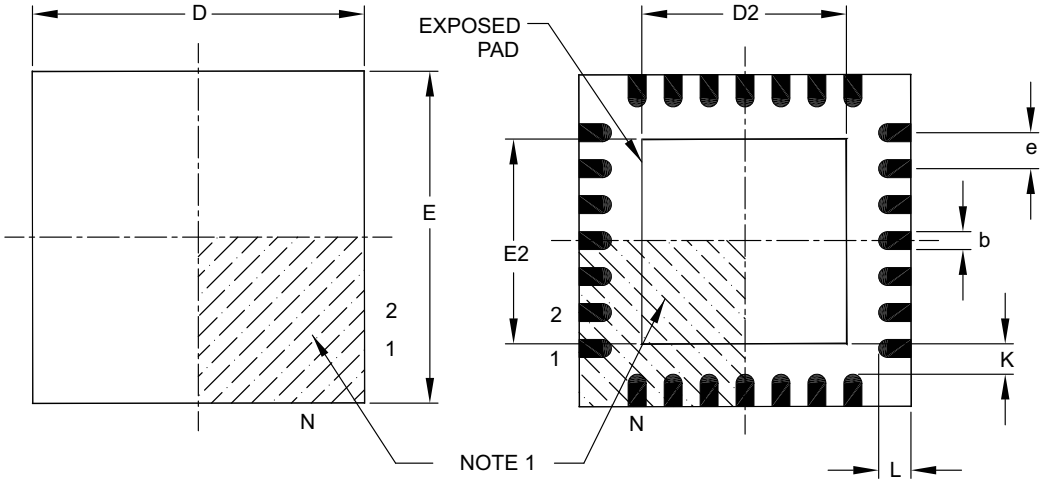
Operating Conditions: -40°C < TA < +125°C (unless otherwise stated)							
Param No.	**Symbol**	**Characteristics**	**Min**	**Typ**	**Max**	**Units**	**Comments**
	VRGOUT	Regulator Output Voltage	—	2.5	—	V	
	VBG	Band Gap Reference Voltage	—	1.2	—	V	
	CEFC	External Filter Capacitor Value	4.7	10	—	μF	Series resistance < 3 Ohm recommended; < 5 Ohm required
	TVREG	Voltage Regulator Start-up Time	—	10	—	μs	POR, BOR or when PMSLP = 1
			—	25	—	μs	PMSLP = 0, WUTSEL<1:0> = 01(1)
			—	190	—	μs	PMSLP = 0, WUTSEL<1:0> = 11(2)
	TPWRT		—	64	—	ms	DISVREG = VDD

Note 1: Available only in devices with a major silicon revision level of B or later (DEVREV register value is 3042h or greater).

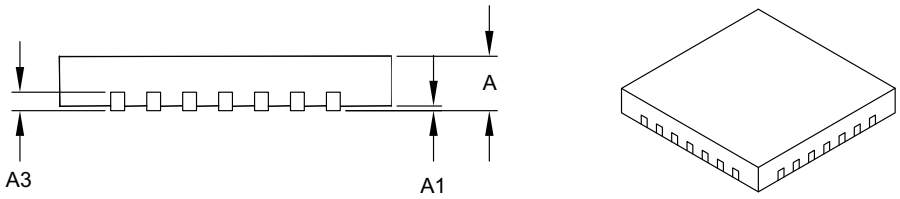
2: WUTSELx Configuration bits setting is applicable only in devices with a major silicon revision level of B or later. This specification also applies to all devices prior to Revision Level B whenever PMSLP = 0.

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW **BOTTOM VIEW**



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Contact Width	b	0.23	0.30	0.35
Contact Length	L	0.50	0.55	0.70
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105B